

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V _{DSS}	-20	V
Gate-Source Voltage	V _{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	I _D	-200 -150	mA
Continuous Drain Current (Note 6) V _{GS} = -2.5V	I _D	-170 -130	mA
Pulsed Drain Current	I _{DM}	-600	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 6)	P _D	330	mW
Thermal Resistance, Junction to Ambient (Note 6)	R _{ΘJA}	377.16	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-100 -50	nA nA	V _{DS} = -16V, V _{GS} = 0V V _{DS} = -5.0V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100 ±1	nA μA	V _{GS} = ±5.0V, V _{DS} = 0V V _{GS} = ±8.0V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-0.45	—	-1.15	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	—	5.5	Ω	V _{GS} = -4.5V, I _D = -100mA
		—	—	7.5		V _{GS} = -2.5V, I _D = -50mA
		—	—	11.5		V _{GS} = -1.8V, I _D = -20mA
		—	—	17.5		V _{GS} = -1.5V, I _D = -10mA
		—	20	—		V _{GS} = -1.2V, I _D = -1mA
Forward Transfer Admittance	Y _{fs}	—	200	—	mS	V _{DS} = -10V, I _D = -0.2A
Diode Forward Voltage (Note 7)	V _{SD}	-0.5	—	-1.2	V	V _{GS} = 0V, I _S = -115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	13.72	27.44	pF	V _{DS} = -15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{OSS}	—	4.01	8.02	pF	
Reverse Transfer Capacitance	C _{rSS}	—	2.34	4.68	pF	
SWITCHING CHARACTERISTICS (Note 8)						
Turn-On Delay Time	t _{d(on)}	—	7.7	—	ns	V _{GS} = -4.5V, V _{DD} = -15V I _D = -180mA, R _G = 2.0Ω
Rise Time	t _r	—	19.3	—		
Turn-Off Delay Time	t _{d(off)}	—	25.9	—		
Fall Time	t _f	—	31.5	—		

- Notes:
6. Device mounted on 1" × 1" FR-4 substrate PCB, with minimum recommended pad layout, single sided.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing.

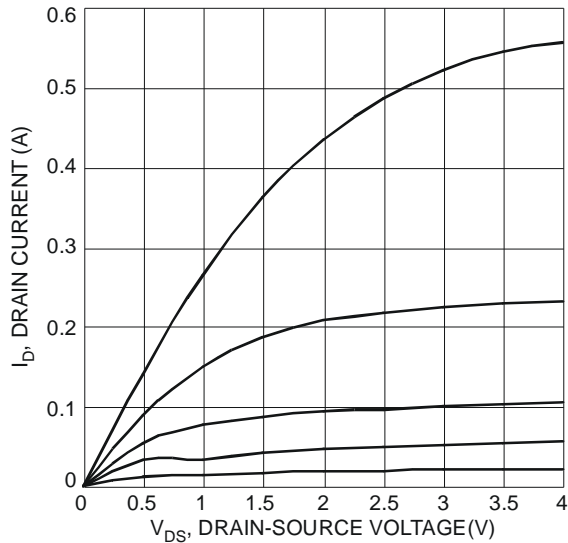


Fig. 1 Typical Output Characteristics

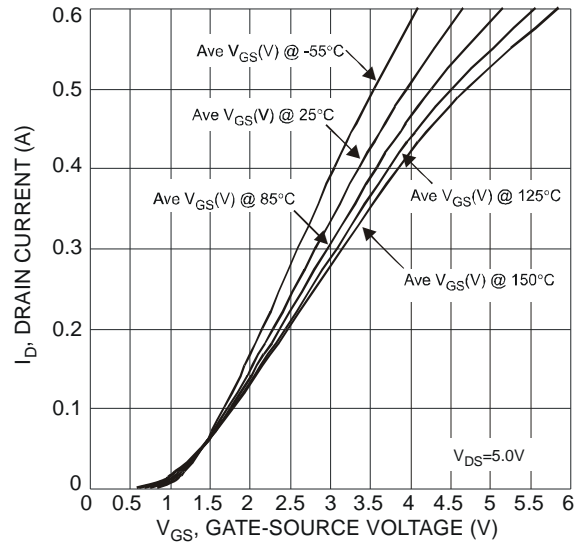


Fig. 2 Typical Transfer Characteristics

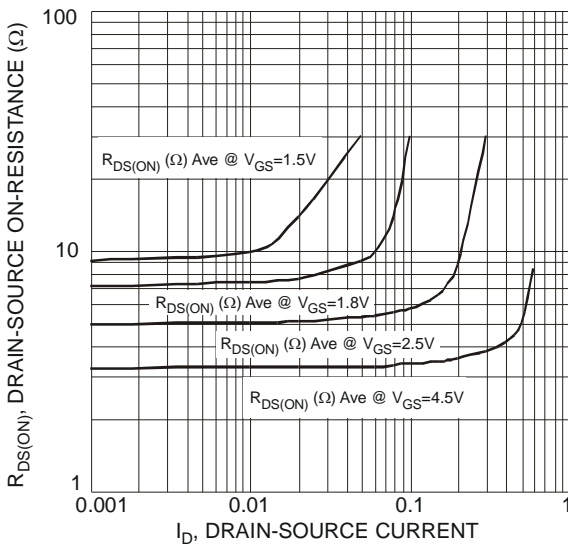


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

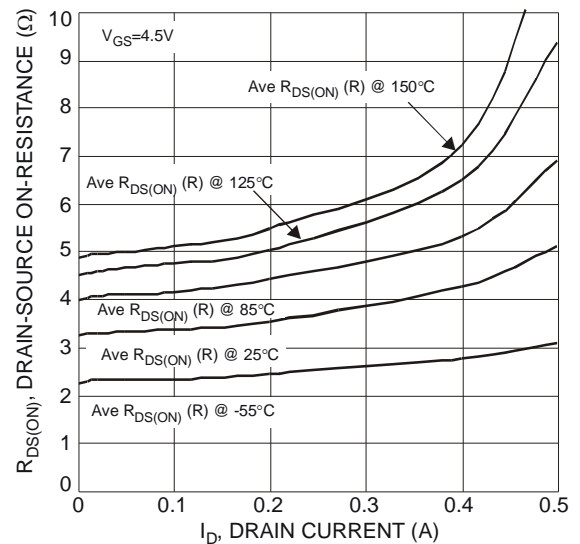


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

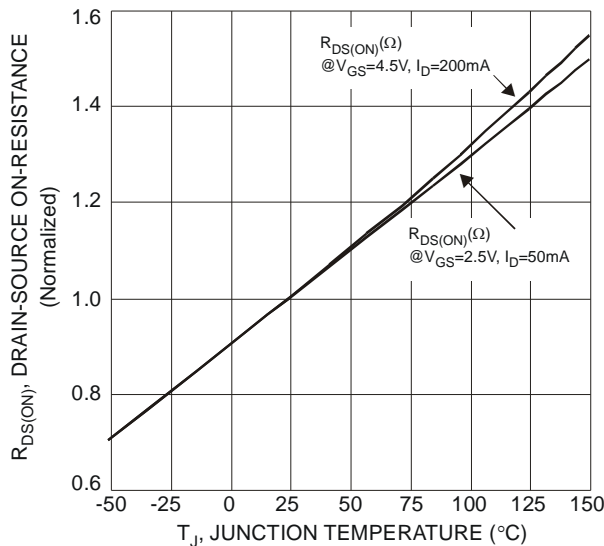


Fig. 5 On-Resistance Variation with Temperature

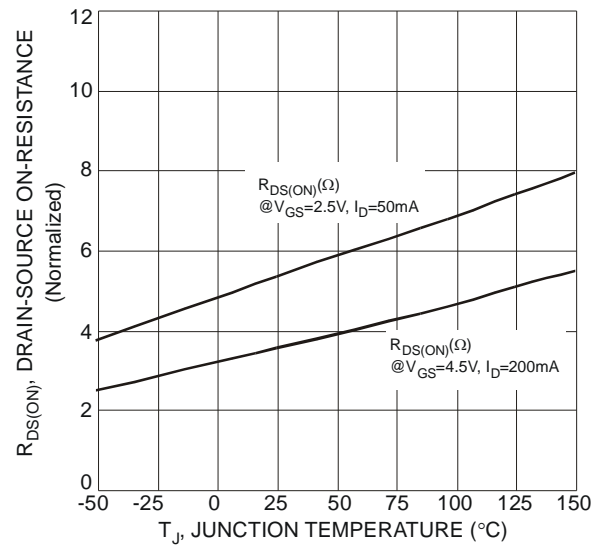


Fig. 6 On-Resistance vs. Temperature

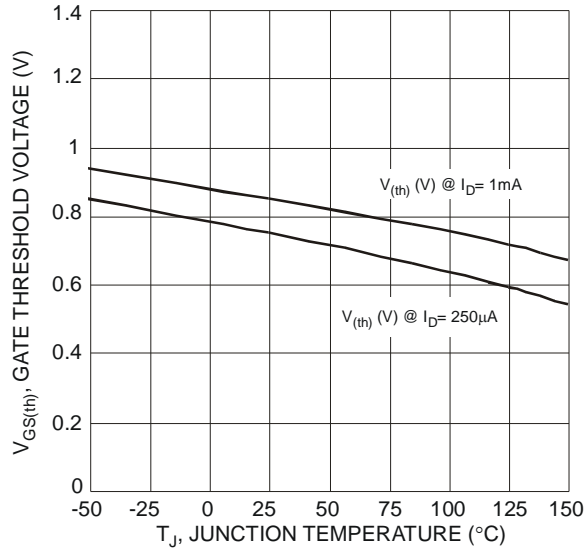


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

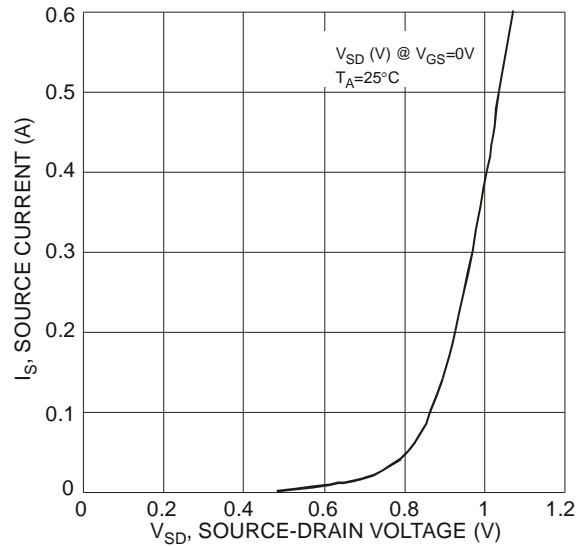


Fig. 8 Diode Forward Voltage vs. Current

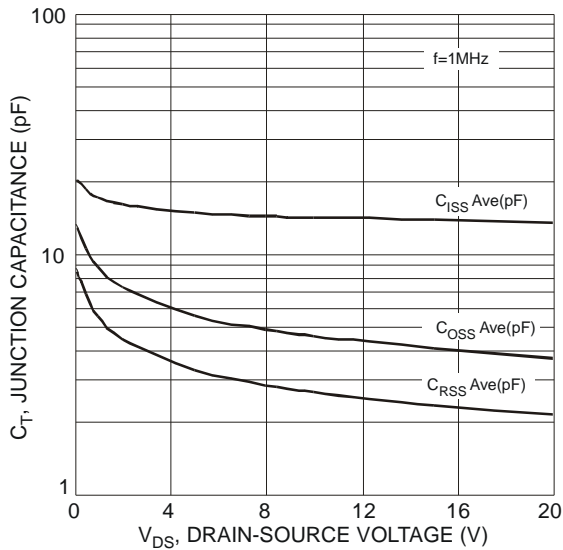


Fig. 9 Typical Junction Capacitance

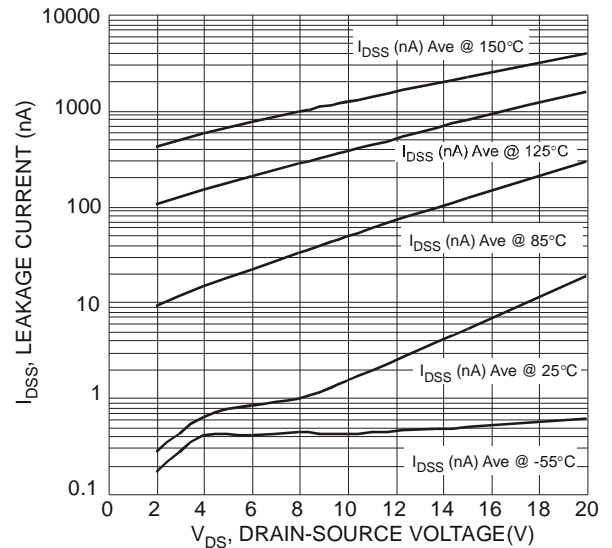


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

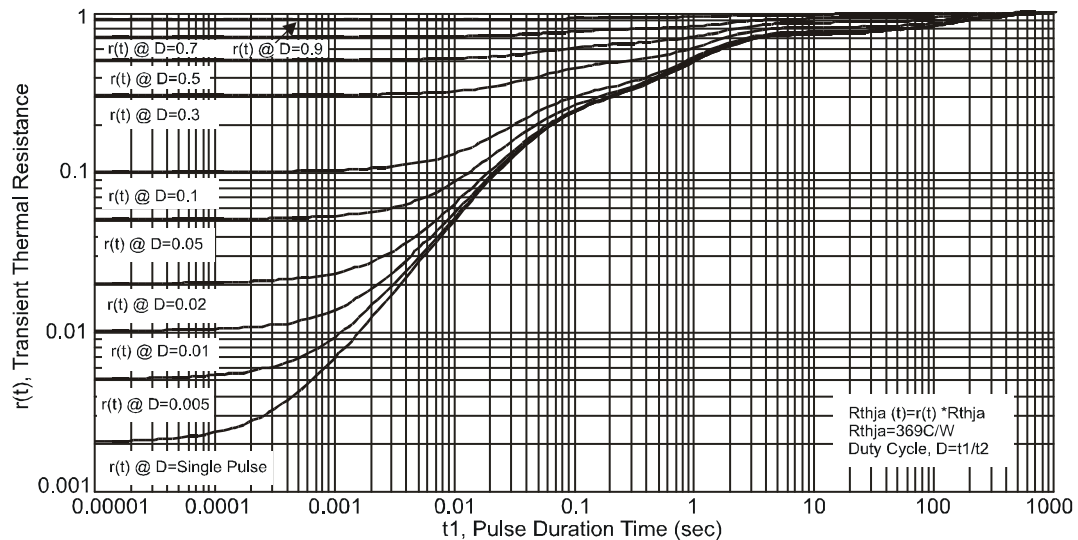
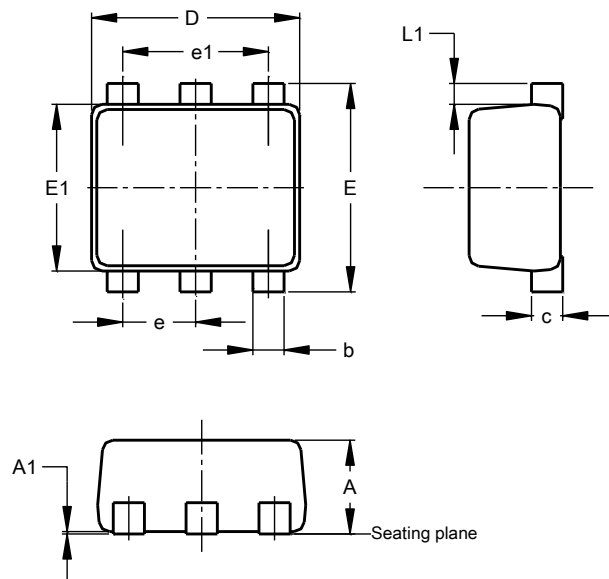


Fig. 11 Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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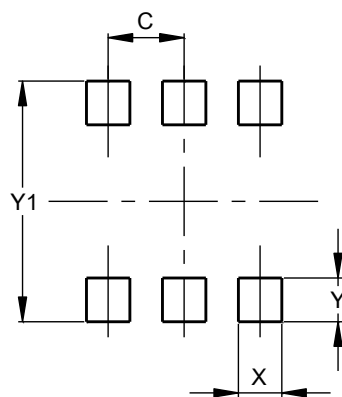


SOT963			
Dim	Min	Max	Typ
A	0.40	0.50	0.45
A1	0.00	0.05	—
b	0.10	0.20	0.15
c	0.120	0.180	0.150
D	0.95	1.05	1.00
E	0.95	1.05	1.00
E1	0.75	0.85	0.80
e	—	—	0.35
e1	—	—	0.70
L1	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT963



Dimensions	Value (in mm)
C	0.350
X	0.200
Y	0.200
Y1	1.100

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